Series: DPAM/DPAF Array, 2.16mm x 2.54mm Differential Pair Interconnect
Description: Perimeter Contacts Common to PCB Ground, 10mm Stack Height

Connector Overview

DPAM/DPAF is a high density 2.16mm x 2.54 mm pitch differential pair array system for high-speed board-to-board applications. DPAM/DPAF configured properly is capable of Rapid I/O, XAUI, PCI Express and SATA Data Rates. DPAM/DPAF High Density Series is tooled in 8, 15 or 23 differential pairs per row and available in three or eight pair rows. This report reflects both standard and optimized SI configurations for hi-speed electrical characteristics specific to a mated 10mm DPAM/DPAF stack height.

Connector System Speed Rating

DPAM/DPAF Array Series, 2.16mm x 2.54mm (.085" x .100") pitch interconnect, 10mm Stack Height

Signaling	Speed Rating
Single-Ended:	**8.0 GHz / 16 Gbps**
Differentia Pair:	
Standard High Density	**7.0 GHz / 14Gbps**
Optimal High Density	**7.0 GHz / 14Gbps**

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded up to the nearest half-GHz level. The up-rounding corrects for a portion of the test board's trace loss, since trace losses are included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/15 Gbps.